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- Replaces SN74AS304
- Maximum Output Skew of 1 ns
- Maximum Pulse Skew of 1.5 ns
- TTL-Compatible Inputs and Outputs
- Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise
- Package Options Include Plastic Small-Outline (D) Package and Standard Plastic (N) 300-mil DIPs

D OR N PACKAGE (TOP VIEW) Q3 16 🛮 Q2 15 Q1 Q4 [GND 3 14 CLR GND II 4 13 V_{CC} GND 5 12 J∨cc Q5 [6] CLK 11 Q6 🛮 7 PRE Q7 9 J Q8

description

The CDC304 contains eight flip-flops designed to have <u>low</u> skew between outputs. The eight outputs (in-phase with CLK) toggle on successive CLK pulses. Preset (PRE) and clear (CLR) inputs are provided to set the Q outputs high or low independent of the clock (CLK) input.

The CDC304 has output and pulse-skew parameters $t_{sk(0)}$ and $t_{sk(p)}$ to ensure performance as a clock driver when a divide-by-two function is required.

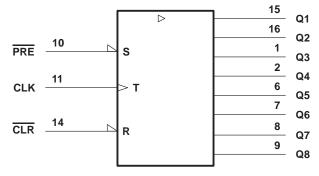
The CDC304 is characterized for operation from 0°C to 70°C.

FUNCTION TABLE

	INPUTS	OUTPUTS		
CLR	PRE	CLK	Q1-Q8	
L	Н	Х	L	
Н	L	X	Н	
L	L	X	L†	
Н	Н	\uparrow	$\overline{\mathtt{Q}}_0$	
Н	Н	L	Q_0	

[†]This configuration does not persist when PRE or CLR returns to its inactive (high) level.

logic symbol‡



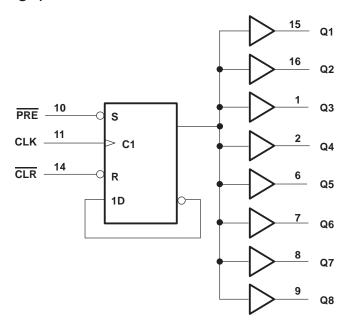
[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



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logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Maximum power dissipation at T _A = 55°C (in still air) (see Note 1): D package	0.77 W
N package	1.2 W
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 300 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
ЮН	High-level output current			-24	mA
loL	Low-level output current			48	mA
fclock	Input clock frequency			80	MHz
TA	Operating free-air temperature	0		70	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	1	TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	$I_I = -18 \text{ mA}$			-1.2	V
Vou	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V
VOH	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -24 \text{ mA}$	2	2.8		V
VOL	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 48 \text{ mA}$		0.3	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1	mA
lн	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20	μΑ
Ι _Ι L	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-0.5	mA
lo [‡]	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.25 \text{ V}$	-50		-150	mA
lcc	V _{CC} = 5.5 V,	See Note 2		45	75	mA

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

timing requirements

			MIN	MAX	UNIT
fclock	Clock frequency			80	MHz
t _w		CLR or PRE low	5		
	Pulse duration	CLK high	4		ns
		CLK low	6		
t _{su}	Setup time before CLK↑	CLR or PRE inactive	6		ns

switching characteristics over recommended operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
f _{max} §				80			MHz	
^t PLH	CLK	Q	P 500 O. C 50 pE	2	6	9	ns	
tPHL	CLK	ď	$R_L = 500 \Omega$, $C_L = 50 pF$	2	6	9		
^t PLH	PRE or CLR	Q	$R_L = 500 \Omega$, $C_L = 50 pF$	3	7	12	ns	
t _{PHL}		Q KL	KL = 500 sz,	3	7	12	115	
tsk(o)	CLK	Q	$R_L = 500 \Omega$, $C_L = 10 pF to 30 pF$, See Figure 2			1	ns	
* * * * *	CLK	CLK	Q1, Q8	B: - 500 O C: - 10 nE to 30 nE			1	
^t sk(p)		Q2-Q7	$R_L = 500 \Omega$, $C_L = 10 pF to 30 pF$			1.5	ns	
t _r						4.5	ns	
t _f						3.5	ns	

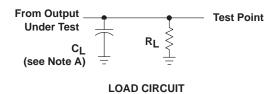
[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

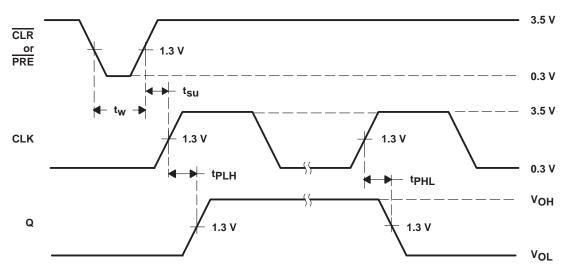


[‡]The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}. NOTE 2: I_{CC} is measured with CLK and PRE grounded, then with CLK and CLR grounded.

[§] f_{max} minimum values are at C_L = 0 to 30 pF.

PARAMETER MEASUREMENT INFORMATION





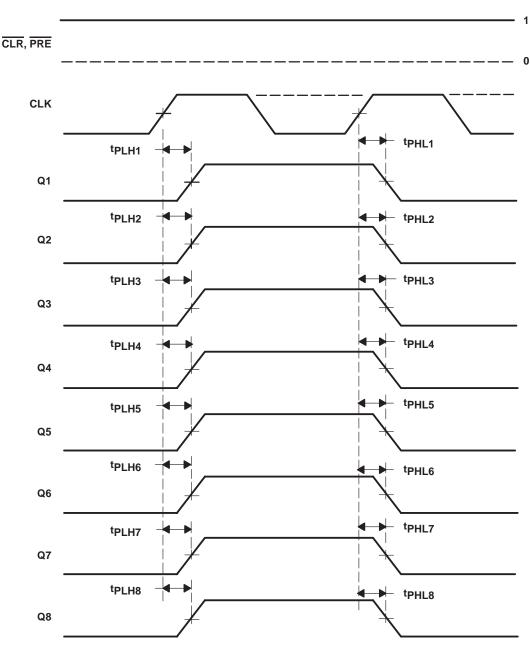
NOTES: A. C_L includes probe and jig capacitance.

B. Input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $t_r = 2.5$ ns, $t_f = 2.5$ ns.

Figure 1. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION



NOTES: A. $t_{sk(0)}$, CLK to Q, is calculated as the greater of the following:

- The difference between the fastest and slowest of tp_{LHn} (n = 1, 2, 3 . . ., 8)
 The difference between the fastest and slowest of tp_{HLn} (n = 1, 2, 3 . . ., 8)
- B. $t_{Sk(p)}$ is defined at the greater of $|t_{PLHn} t_{PHLn}|$ (n = 1, 2, 3, ..., 8).

Figure 2. Waveforms for Calculation of $t_{sk(0)}$ and $t_{sk(p)}$

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